

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

ON Semiconductor®

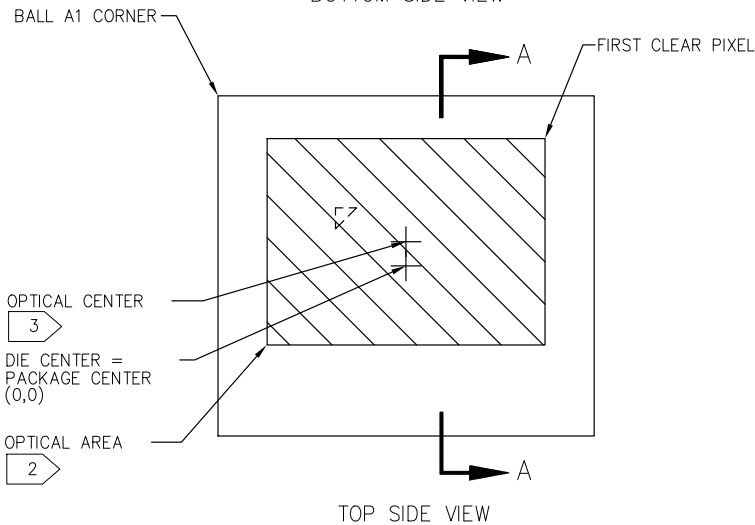
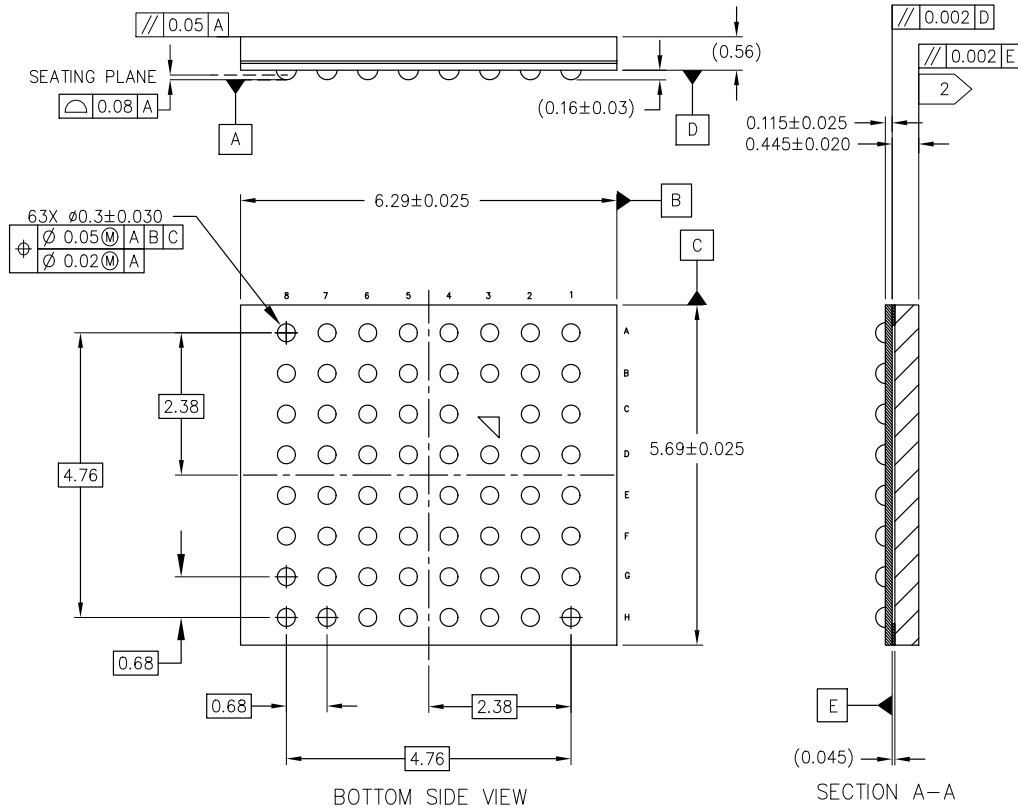


ODCSP63 6.29x5.69

CASE 570BU

ISSUE O

DATE 19 OCT 2015



NOTES	
1	DIMENSIONS IN MM. DIMENSIONS IN () ARE FOR REFERENCE ONLY.
2	MAXIMUM ROTATION OF OPTICAL AREA RELATIVE TO PACKAGE EDGES: 0.1° MAXIMUM TILT OF OPTICAL AREA RELATIVE TO SUBSTRATE PLANE [D]: 2µm. MAXIMUM TILT OF COVER GLASS RELATIVE TO OPTICAL AREA PLANE [E]: 2µm.
3	OPTICAL CENTER OFFSET FROM PACKAGE CENTER; X=0 Y=0.405 ±0.075 WITH RESPEC TO PACKAGE CENTER.

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